

# SMD Power Inductor

**TMPC252010H-Series**

## 1. Features

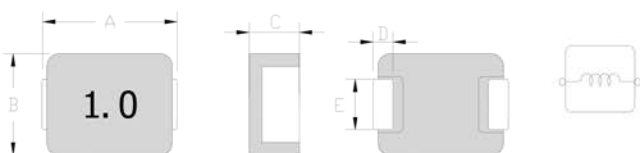
1. Small and Low profile inductor.
2. It corresponds to High current.
3. Simple and Shield structure.
4. Available tape and reel for auto insertion.



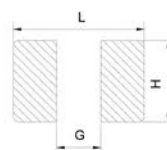
## 2. Applications

For small DC/DC converter  
(cellular Phone, LCD/LED/OLED display, HDD, DSC etc).

## 3. Dimensions



### Recommend PC Board Pattern



Series	A(mm)	B(mm)	C(mm)	D(mm)	E(mm)
TMPC252010H	2.6±0.3	2.0±0.2	1.0MAX	0.6±0.2	1.0±0.2

L(mm)	G(mm)	H(mm)
3.0	1.2	1.4

## 4. Part Numbering



A: Series  
 B: Dimension  
 C: Type  
 D: Inductance  
 E: Inductance Tolerance

AxBxC  
 Carbonyl Powder  
 1.0=1.00uH  
 M=±20%, Y=±30%

## 5. Specification

Part Number	Inductance L0 (uH)±30% @ 0 A	I rms (A) Typ.	I sat (A) Typ.	DCR(mΩ) Typ.@25°C	DCR(mΩ) Max.@25°C
TMPC252010H-1R0YG	1.00	2.5	2.7	85	98
TMPC252010H-1R5YG	1.50	2.1	2.3	110	128
TMPC252010H-2R2YG	2.20	1.8	2.0	205	242
TMPC252010H-3R3YG	3.30	1.5	1.7	295	340
TMPC252010H-4R7YG	4.70	1.3	1.5	348	402
TMPC252010H-100YG	10.0	0.8	0.9	755	870

Note:

1. Test frequency : L : 1MHz /1.0V;
2. All test data referenced to 25°C ambient.
3. Testing Instrument : L/Q: HP4284A, CH11025, CH3302, CH1320 ,CH1320S LCR METER / Rdc: CH16502, Agilent33420A MICRO OHMMETER.
4. Heat Rated Current (I<sub>rms</sub>) will cause the coil temperature rise approximately Δt of 40°C (keep 1min.).
5. Saturation Current (I<sub>sat</sub>) will cause L0 to drop 30% typical. (Keep quickly).
6. The part temperature (ambient + temp rise) should not exceed 125°C under worst case operating conditions. Circuit design, component, PCB trace size and thickness, airflow and other cooling provisions all affect the part temperature. Part temperature should be verified in the end application.
7. Special inquiries besides the above common used types can be met on your requirement.

## 10. Typical Performance Curves

